

TITLE
POLISHING APPARATUS AND POLISHING METHOD

ABSTRACT

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A polishing apparatus includes a polishing table which supports a polishing pad, a polishing head which polishes a substrate by pressing the substrate against a polishing surface of the polishing pad, a pad temperature measuring device which measures a temperature of the polishing surface, a pad temperature adjusting device which adjusts the temperature of the polishing surface, and a control device which controls the operation of the pad temperature adjusting device based on the temperature of the polishing surface measured by the pad temperature measuring device. The pad temperature adjusting device includes a pad heater which is disposed to be separated upward from the polishing surface, and the pad heater includes a longitudinal portion which extends in a substantially radial direction of the polishing pad and a slit-shaped injection port which is formed in a longitudinal direction of the longitudinal portion and injects a heating fluid toward the polishing surface.

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FIG. 1